Malcom

SOLDER-PASTE WETTING TESTER

SP-2

Evaluate Solderability of solder paste, component and circuit board

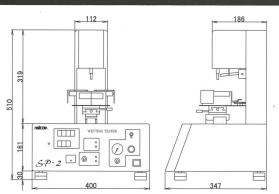


SPECIAL FEATURES

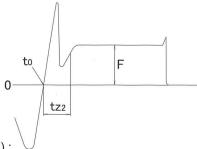
- All wetting process can be observed from glass windows.
- Can simulate reflow oven profile with hot air and N₂ purge.
- Analyze wetting time and force with exclusive software.
- Can test and evaluate solder paste, PC board and parts lead.
- "Wetting Balance Measuring Method" and "Quick Heating Method" are possible optionally.

DIMENSION

unit: mm



WAVE FORM EXAMPLE



Wetting force F (mN):

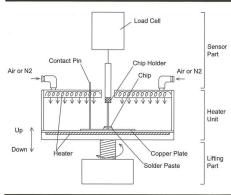
Solder paste was wetted completely, and the wetting force became stable.

Zero cross point to:

Solder paste starts melting, and its load changes from pushing force to pulling force.

Wetting time tz₂ (s): Taking time from the point, solder paste starting to wet to wetting force being 86%.

MEASUREMENT PROCEDURES



- 1. Solder paste is printed onto a copper plate, which is then fastened to the heater table.
- 2. A test pieces (copper plate) attached to the load cell.
- 3. The heater table rises up until the printed solder paste makes contact with the test piece.
- 4. The test piece inserts the preset amount into the solder paste and stays for 10sec.
- 5. The temperature of the heater unit rises according to the preset temperature profile.
- The solder paste reflows and the test piece wets, melting and wetting forces are measured and drawn curve.
- 7. The heater table lowers down and the measurement is completed.

SPECIFICATIONS				
Load Sensor	Sensor Technology	Electro-balance method	Temp. Profile Settings	①Preheat time ②Preheat temp. ③Thermal up speed (standard: 3°C/sec.) ④Max. temp. ⑤Max. temp. time
	Sensor Limits	-5.00gf ~ +10.00gf		
	Sensor Accuracy * 1	士 (10mgf + 1digit)	Air Supply	Air pressure: 0.2~0.5MPa (approx. 2~5kgf/cm²) Adjustable air pressure: 0.2MPa (approx. 2kgf/cm²)
	Resolution	Under 900mgf : 0.001gf 900mgf or more : 0.005gf		
Temp. Sensor	Measurement Range	0 ~ 300℃	Table Lifting	Automatic: Control by PC Manual: Operated with up / down switch (can select 3 steps speed)
	Measurement Accuracy	± 3°C		
Heater Unit	Temp.	0 ~ 300℃	Power Supply	AC 100V 50 / 60 Hz 700W
	O ₂ Concentration	Simple airtight heater unit with Nipple for N₂ purge test	Weight	Approx. 20kg
Melting Point Setting		Preset solder paste melting point	Option	Menisco tools, Quick Heating Method, Micro scope, № Flow Meter : NAM-100, Video Camera Capture System : VDM-1
Digital Output		RS232C (Malcom format)		

^{* 1} Load sensor accuracy is exclusive of errors, such as oscillation.

Spiral Viscometer Soldering Process Devices Representative

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^{*}The above specifications are subject to change without notice.